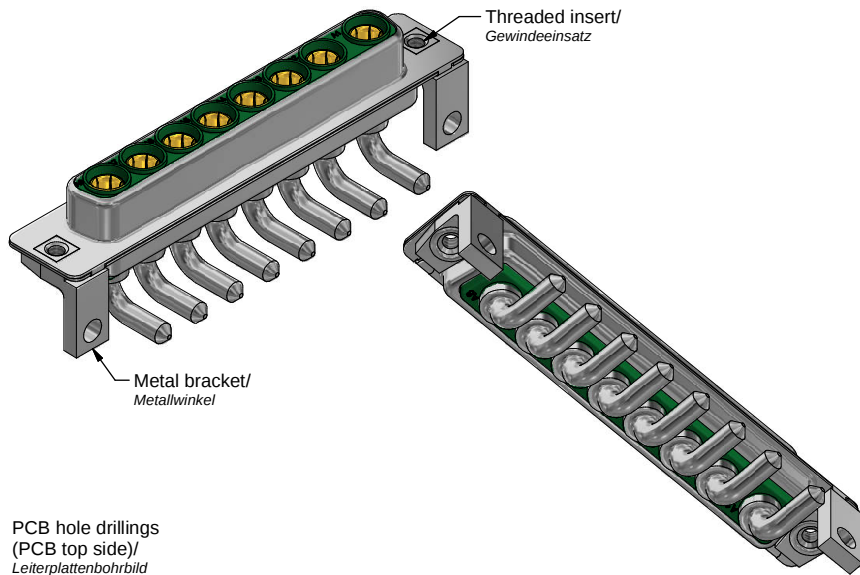
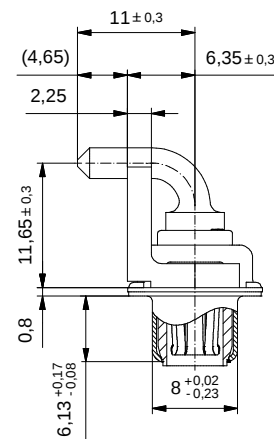
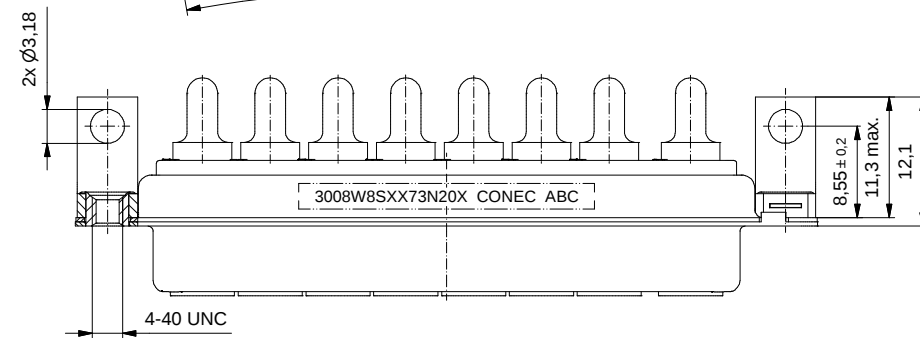
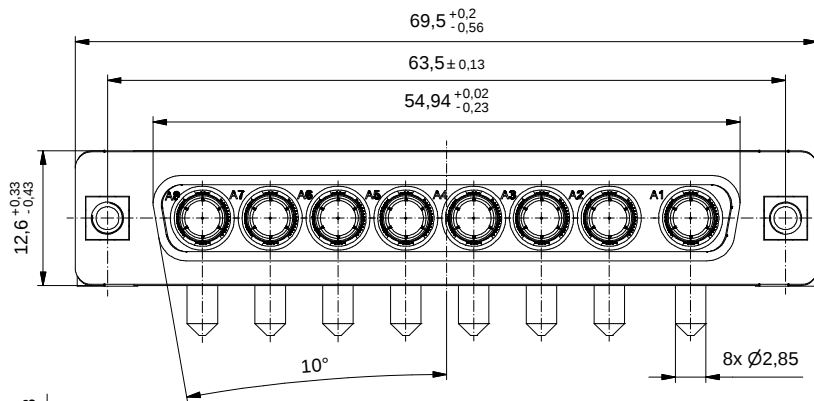
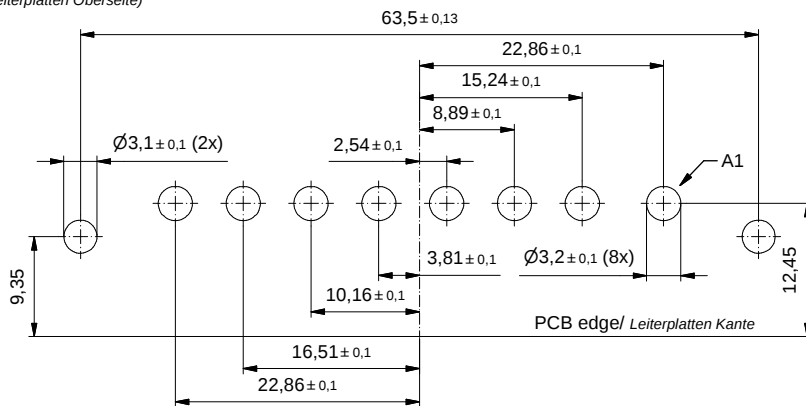




PCB hole drillings
(PCB top side)/
Leiterplattenbohrbild
(Leiterplatten Oberseite)



Technical specification/

Technische Daten:

Dielectric withstanding voltage/ Spannungsfestigkeit:	1000 V, 50 Hz 1 min.
Current rating/ Strombelastbarkeit:	High power contact/ 20 A Hochstromkontakt
Insulation resistance/ Isolationswiderstand:	≥ 5 GΩ
Temperature range/ Temperaturbereich:	- 55 °C ... + 125 °C
Mating cycles/ Steckzyklen:	Quality class 3 = 50 Gütestufe 3

Materials/

Werkstoffe:

Contact/ Kontakt:	Cu alloy, mating area/ Steckbereich:	Au over Ni
	termination side/ Anschluss Seite:	Sn over Ni
Insulator/ Isolierkörper:	PBT GF UL 94 V-0, green/grün	
Shell/ Gehäuse:	Steel, Sn over Ni	
Metal bracket/ Metallwinkel:	GD-Zn, Sn over Ni	
Threaded insert/ Gewindeeinsatz:	Cu alloy, Sn over Ni	

Installation specification/

Montagedaten:

Recommended torque value for thread/ Empfohlenes Drehmoment für Gewinde:	max. 6 in.LB/ max. 67 Ncm
---	------------------------------

Part no. / Part marked/ Art.-Nr. / Bedruckung:	Contact plating/ Kontakt Veredelung:		
3008W8SXX73N20X	High power contact 20 A/ Hochstromkontakt 20 A:	plating, mating area/ Veredelung, Steckbereich:	gold flash over nickel Gold über Nickel
		plating, termination side/ Veredelung, Anschluss Seite:	tin over nickel Zinn über Nickel
Index: a Original	Scale/ Maßstab: 2:1		
RoHS compliant/ konform			
		dwg no / Z.-nr.:	13K1A6383
			DIN-A3
			1 / 1